



PATENT APPLICATION

GP/2826

## IN THE U.S. PATENT AND TRADEMARK OFFICE

December 6, 2002

Applicant(s) : Chikao IKENAGA et al.

Title (TRADEMARK) : FRAME FOR SEMICONDUCTOR PACKAGE INCLUDING PLURAL LEAD FRAMES HAVING THIN PARTS OR HOLLOWS ADJACENT THE TERMINAL ROOTS

Serial No. : 09/850 213 Group: 2826

Confirmation No. : 9610

Filed : May 7, 2001

Examiner: Greene

Atty. Docket No. : OPS C-533

Assistant Commissioner for Patents  
Washington, DC 20231

Sir:

Herewith is an amendment in the above-identified application.

Statement(s) re small entity status submitted previously.  
 Statement(s) re small entity status enclosed.  
 No additional filing fee is required.  
 The additional filing fee has been calculated as shown below:

For	No. Filed	No. Extra	(X) LG Entity	RATE	( ) SM Entity	Fee
Basic Fee				\$740.00	\$370.00	\$
Total Claims	(21 - 20 = 1)		x \$ 18.00		x \$ 9.00	18.00
Indep. Claims	(5 - 4 = 1)		x \$ 84.00		x \$ 42.00	84.00
[ ] Multiple Dep. Claim			+ \$280.00		+ \$140.00	
* * * TOTAL FILING FEE * * *						\$ 102.00

A Check for \$102.00 is enclosed to cover fees.  
 Please credit any overpayment, or charge any additional filing fee or application processing fee required under 37 CFR 1.16 or 1.17 by this communication, to Deposit Account No. 06-1382. A duplicate copy of this sheet is enclosed.

IN DUPLICATE

Respectfully submitted,

LLC/cc

Liane L. Churney Reg. No. 40 694

Encl: Listed above

## CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Assistant Commissioner for Patents, Washington, DC 20231, on December 6, 2002.

Respectfully submitted,

Liane L. Churney

130.0112



PATENT APPLICATION

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International Application No.: N/A

International Filing Date: N/A

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AMENDMENT AND RESPONSE TO RESTRICTION REQUIREMENT

Sir:

In response to the Office Action dated November 6, 2002,  
Applicants amend as follows:

IN THE CLAIMS

Please amend Claim 4 as follows. A marked-up version of the amended claim is enclosed herewith, showing the changes made by the current amendment.

4. (Amended) A frame for forming individual semiconductor packages, said frame comprising a plurality of lead frames arranged in a matrix and semiconductor devices respectively mounted on die pads supported on the individual lead frames by suspending leads, each said lead frame having a metal lead which defines a boundary between said lead frame and an adjacent lead frame, and pairs of terminals project in opposite directions from each said lead disposed between an adjacent pair of lead frames, wherein roots of the respective

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